Amendments to the Claims

Claims 1-9 **(Canceled)**

Claim 10 **(Currently Amended)** An analog resistive-film type thin-frame touch panel, comprising:

a lower-side electrode member having

a lower-side transparent insulating base member,

a lower-side transparent electrode on a part of a top face of ~~a~~ the lower-side transparent insulating base member,

a pair of lower-side bus bars disposed on two parallel sides of the lower-side transparent electrode, and

lower-side external terminal connection portions disposed on a portion other than the lower-side transparent electrode and connected to the lower-side bus bars; ~~and~~

an upper-side electrode member having

a flexible upper-side transparent insulating base member,

an upper-side transparent electrode on a part of a bottom face of ~~an~~ the flexible upper-side transparent insulating base member ~~having flexibility~~,

a pair of upper-side bus bars disposed on two parallel sides of the upper-side transparent electrode, and

upper-side external terminal connection portions disposed on a portion other than the upper-side transparent electrode and connected to the upper-side bus ~~bars,~~ bars; and

an insulative spacer, wherein

the lower-side electrode member and the upper-side electrode member ~~being~~ are disposed facing each other via ~~an~~ the insulative spacer ~~in~~ such ~~a way~~ that the upper-side bus bars and the lower-side bus bars are arranged in a square pattern, and ~~being~~ the lower-side electrode member and the upper-side electrode member are bonded at peripheral portions, ~~wherein~~

the lower-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm, ~~while~~

the upper-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm, and

~~in each of the upper-side electrode member and the lower-side electrode member,~~ the metal thin wires and a portion of each of the upper-side and lower-side transparent insulating base members around the metal thin wires are covered with a conductive paste so that the metal thin wires are respectively fixed onto the upper-side transparent insulating base member and the lower-side transparent insulating base member ~~through a conductive past~~.

Claim 11 **(Previously Presented)** The thin-frame touch panel as defined in Claim 10, wherein

the lower-side electrode member further has lower-side routing circuits disposed on the portion other than the lower-side transparent electrode, for connecting the lower-side bus bars and the lower-side external terminal connection portions,

the upper-side electrode member further has upper-side routing circuits disposed on the portion other than the upper-side transparent electrode, for connecting the upper-side bus bars and the upper-side external terminal connection portions, and

the lower-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm and the upper-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm.

Claim 12 **(Currently Amended)** The thin-frame touch panel as defined in Claim 11, wherein the metal thin wires constituting each of the lower-side routing circuits and the upper-side routing circuits are extended to ~~outsides~~ outside of the lower-side electrode member and the upper-side electrode member to constitute the lower-side external terminal connection portions and the upper-side external terminal connection portions.

Claim 13 **(Currently Amended)** The thin-frame touch panel as defined in Claim 10, wherein

the lower-side bus bars and the lower-side external terminal connection portions are directly ~~connected~~ connected, and ~~the lower-side bus bars and~~ the lower-side external terminal connection portions are also formed by ~~from~~ metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm, ~~while~~

the upper-side bus bars and the upper-side external terminal connection portions are directly ~~connected~~ connected, and ~~the upper-side bus bars and~~ the upper-side external terminal

connection portions are also formed by ~~from~~ metal thin wires having a circular cross section and a wire diameter of 30 to 100 μm, and

the metal thin wires of the upper-side external terminal connection portions and the metal thin wires of the lower-side external terminal connection portions are extended to ~~outsides~~ outside of a region where the lower-side electrode member and the upper-side electrode member are bonded to each other.

Claim 14 **(Canceled)**

Claim 15 **(Currently Amended)** The thin-frame touch panel as defined in Claim ~~10,~~ 11, wherein ~~in the upper-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the upper-side transparent insulating base member and in the lower-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the lower-side transparent insulating base member~~ a part of each of the metal thin wires is respectively embedded in one of the upper-side and lower-side transparent insulating base members by melting and solidification of the upper-side and lower-side transparent insulating base members.

Claim 16 **(Currently Amended)** The thin-frame touch panel as defined in Claim 15, wherein

~~a lower-side covering layer formed by being covered with the conductive paste in~~ at least ~~either~~ one ~~of a~~ of bend ~~portion~~ portions of the lower-side routing ~~circuit~~ circuits and the lower-side bus ~~bar in~~ bars of the lower-side electrode member are covered with the conductive paste to form a lower-side covering layer that has a width 2 to 5 times larger than ~~a~~ the wire diameter of the metal thin ~~wire in~~ wires of the lower-side electrode member, ~~and~~

~~a lower-side covering layer formed by being covered with the conductive paste in~~ other portions of the lower-side electrode member are covered with the conductive paste to form a lower-side covering layer that has a width 1 to 5 times larger than the wire diameter of the metal thin ~~wire in~~ wires of the lower-side electrode member, ~~while~~

~~an upper-side covering layer formed by being covered with the conductive paste in~~ at least ~~either~~ one ~~of a~~ of bend ~~portion~~ portions of the upper-side routing circuits and the upper-side bus bars ~~in~~ of the upper-side electrode member are covered with the conductive paste to form an

upper-side covering layer that has a width 3 to 5 times larger than ~~a~~ the wire diameter of the metal thin ~~wire in~~ wires of the upper-side electrode member, and

~~an upper-side covering layer formed by being covered with the conductive paste in~~ other portions of the upper-side electrode member are covered with the conductive paste to form an upper-side covering layer that has a width 2 to 5 times larger than the wire diameter of the metal thin ~~wire in~~ wires of the upper-side electrode member.

Claim 17 **(Currently Amended)** The thin-frame touch panel as defined in Claim 10, wherein the metal thin wires have a specific resistance value of ~~the metal thin wire is~~ $20 \times 10^{-6}\ \Omega \cdot cm$ or less.

Claim 18 **(Currently Amended)** The thin-frame touch panel as defined in Claim 17, wherein the ~~metal thin wire on the transparent insulating base member and its periphery are covered with a~~ conductive paste has ~~with~~ a specific resistance value of $1 \times 10^{-4}\ \Omega \cdot cm$ or less.

Claim 19 **(Currently Amended)** The thin-frame touch panel as defined in Claim ~~10,~~ 11, wherein ~~a thin-frame of the touch panel is an interconnection region in the upper-side transparent insulating base member and the lower-side transparent insulating base member of the touch panel, in which~~ the lower-side and upper-side bus bars, the lower-side and upper-side routing circuits, and the lower-side and upper-side external terminal connection portions are formed at peripheries of the lower-side and upper-side transparent insulating base members and form an interconnection region of the upper-side and lower-side transparent insulating base members, the innerconnection region being formed such that its thin-frame width size as seen from an external form thereof is 2 mm or lower at least on three sides.